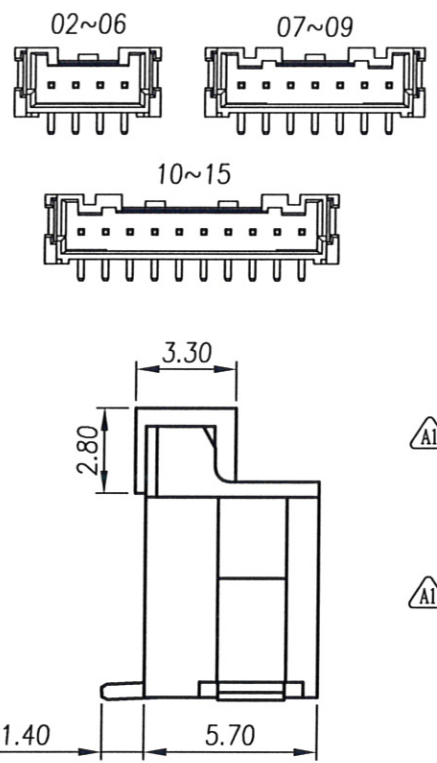


**RoHS Compliant**



REV	MODIFICATION	DATE	DRAW
A0	Release To Production	2014.05.14	Michelle
A1	Release To ECN20150317	2015.03.30	Michelle
A2	Release To ECN20150807	2015.08.18	Michelle

**Specification**

- Current Rating: 3A AC/DC(Max) AWG#22
- Voltage Rating: 250V AC/DC
- Contact Resistance: 20mΩ Max.
- Insulation Resistance: 1000MΩ Min.
- Dielectric Withstanding Voltage: AC800V/Minute
- Operating Temperature: -25°C~+85°C

**Material:**

- Housing: High Temperature Thermoplastic UL94V-0
- Tab: Copper Alloy T=0.40mm
- Contact Pin: Copper Alloy SQ. Pin 0.50mm

**Finish:**

- Housing: Natural
- Tab: Bright Tin Plated Over Nickel
- Contact Pin: See P/N Option

**Part No.:** AS06400 XX 5 X X 2

**No. Of Pin:** 02~15

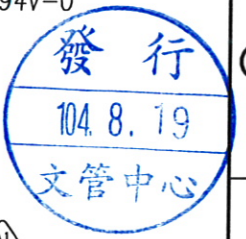
**Packing:**

- T&R With Cap
- T&R Without Cap
- Tube With Cap
- Tube Without Cap

**Housing Material:** 5: HTN UL94V-0 Natural

**Plating:**

- Bright Tin Plated Over Nickel
- Gold Plated Over Nickel



PIN	DIM.A	DIM.B	DIM.L
02	2.00	8.00	4.50
03	4.00	10.00	
04	6.00	12.00	
05	8.00	14.00	
06	10.00	16.00	
07	12.00	18.00	
08	14.00	20.00	
09	16.00	22.00	
10	18.00	24.00	
11	20.00	26.00	
12	22.00	28.00	
13	24.00	30.00	
14	26.00	32.00	
15	28.00	34.00	

**金上達科技股份有限公司**  
**GOLDENSUNDA TECHNOLOGY CO., LTD**

**TOLERANCE UNLESS OTHERWISE SPECIFIED**

.x± 0.35	x.± 2'	PROJ.	TITLE: Wire To Board Wafer 2.00mm 180° SMT Single Row
.xx± 0.25	.x± 1'	APR. C.F.Liao 20150819	PART NO. AS06400XX5XX2
.xxx± 0.15	.xx± 0.5'	CHK. Abel 20150819	DWG NO. AS06400XX5XX2
		DRA. Michelle 20150819	UNITS: mm

**CUSTOMER DRAWING**

SIZE: **A4** SCALE: 4:1 SHEET 1 / 1 REV A2 V